

COMPOSITE COPPER FOIL, PROCESS FOR PREPARING THE SAME,
AND COPPER-CLAD LAMINATE AND PRINTED WIRING
BOARD USING THE SAME

ABSTRACT

This invention provides a composite foil comprising
an organic release layer between a metal carrier layer
5 and an ultra-thin copper foil, and a process for
producing such composite foils comprising the steps of
depositing the organic release layer on the metal carrier
layer and then forming an ultra-thin copper foil layer on
said organic release layer by electrodeposition. The
10 organic release layer preferably is a nitrogen-containing
compound, a sulfur-containing compound, or a carboxylic
acid, which provides a uniform bond strength which is
adequate to prevent separation of the carrier and ultra-
thin copper foil during handling and lamination, but
15 which is significantly lower than the peel strength of a
copper/substrate bond, so that the carrier can easily be
removed after lamination of the composite foil to an
insulating substrate. The invention also includes
laminates made from such composite foils and printed
20 wiring boards made from such laminates.

Figure 1